

ABSTRACT OF THE DISCLOSURE

A circuit board assembly with an array of closely spaced circuit components mounted thereon. The board has a pattern of conductive strips on both front and back faces and the strips are connected through the board by thermally conductive vias. The circuit components are mounted on one side of the board and a layer of thermally conductive, double-sided adhesive tape is laid over the conductive strips on both faces of the board. Heat sinks are then applied against the tape on both sides of the board to conduct heat from the board through the tape.